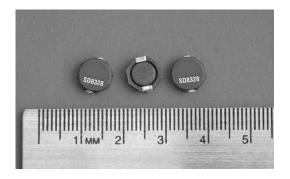
Effective August 2017 Supersedes September 2011

# SD8328 Low profile shielded drum core power inductors



#### **Product features**

- Low profile shielded drum core
- 9.5 mm x 8.3 mm x 3.0 mm surface mount inductor
- Ferrite core material
- Inductance range from 2.7  $\mu H$  to 100  $\mu H$
- Current range from 0.8 A to 6.6 A
- Frequency range up to 1 MHz

#### Applications

- Buck or boost inductor
- Noise filtering output filter chokes
- Notebook and laptop power/display
- LCD Monitors/displays/televisions
- Battery chargers, LCD bias supplies
- Battery and Industrial power systems
- Computer, DVD and media players
- Portable power devices
- DC-DC converters

#### **Environmental data**

- Storage temperature range (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant





# **Product specifications**

Part Number	Rated Inductance (µH)	0CL <sup>1</sup> μH±30%	Irms <sup>2</sup> (A)	lsat <sup>3</sup> (A)	DCR mΩ @ +20 °C Typ	DCR mΩ @ +20 °C Max	K-factor⁴
SD8328-2R5-R	2.5	2.7	6.6	4.5	12	15.6	43
SD8328-3R3-R	3.3	3.4	6.1	4.0	14	18.0	33
SD8328-4R7-R	4.7	5.0	4.5	3.6	19	24.7	23
SD8328-7R3-R	7.3	7.6	3.4	2.9	30	39	15
SD8328-100-R	10	9.1	3.3	2.6	36	45	11
SD8328-150-R	15	14.5	2.35	2.0	53	69	7.2
SD8328-220-R	22	21.1	1.85	1.7	76	99	4.9
SD8328-330-R	33	31.9	1.45	1.4	120	156	3.3
SD8328-470-R	47	44.9	1.30	1.2	150	194	2.3
SD8328-680-R	68	64.2	0.98	1.0	220	286	1.6
SD8328-101-R	100	97.0	0.80	0.8	330	430	1.1
					1		

1. Open Circuit Inductance Test Parameters: 100 kHz, 0.1 Vrms, 0.0 Adc.

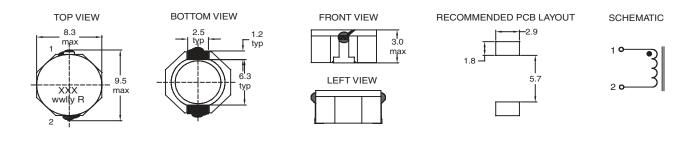
2. Irms: DC current for an approximate  $\Delta T$  of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125  $^{\circ}\text{C}$  under worst case operating conditions verified in the end application. 3. Isat Amps peak for approximately 35% rolloff (@ +25 °C)

4. K-factor: Used to determine  $B_{p-p}$  for core loss (see graph).  $B_{p-p} = K^*L^*\Delta I, B_{p-p} \ (mT), K: (K factor from table), L: (Inductance in \muH), <math display="inline">\Delta I$  (Peak to peak ripple current in Amps).

5. Part Number Definition: SD8328-xxx-R

SD8328 = Product code and size; -xxx = Inductance value in  $\mu$ H; R = decimal point; If no R is present, third character equals number of zeros. -R suffix = RoHS compliant

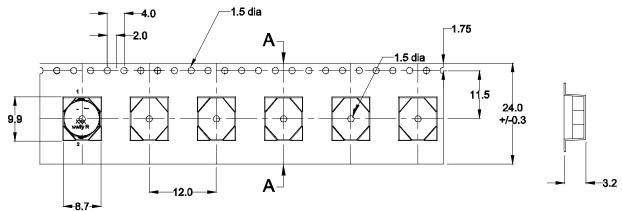
# **Dimensions-mm**



Part Marking: xxx = Inductance value in µH. (R = Decimal point). If no R is present, third character = number of zeros willy - or - willy = Date code Do not route traces or vias underneath the inductor

#### R = Revision level

### **Packaging information-mm**

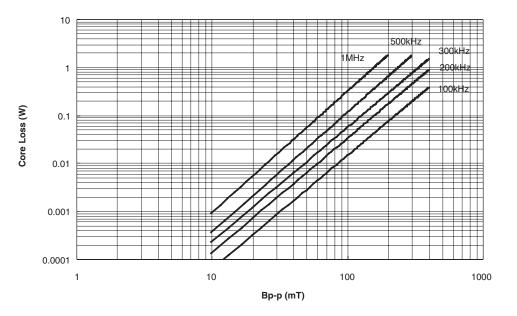


Supplied in tape-and-reel packaging, 1280 parts per reel, 13" diameter reel.

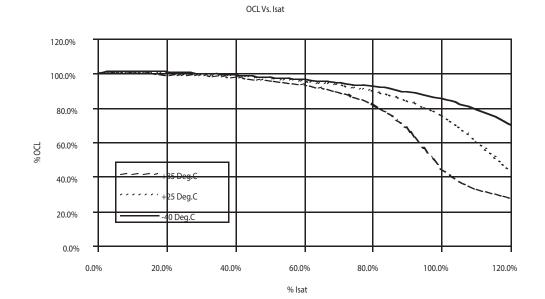
# Temperature rise vs total loss



# Core loss vs Bp-p



# Inductance characteristics



# **Solder Reflow Profile**

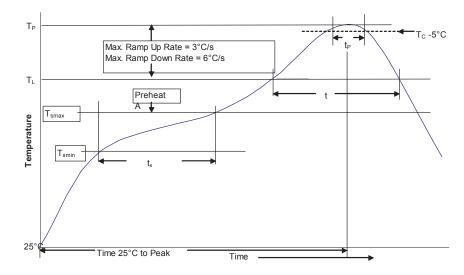


Table 1 - Sta	ndard SnF	Pb Solder (T <sub>C</sub> )	
	Volume	Volume	
Package	mm <sup>3</sup>	mm <sup>3</sup>	
Thickness	<350	≥350	
<2.5mm	235°C	220°C	
0.5	220°C	220°C	
≥2.5mm	220 0	220 0	
≥2.5mm Table 2 - Lea	d (Pb) Fre	e Solder (T <sub>C</sub> )	
Table 2 - Lea	d (Pb) Fre Volume	e Solder (T <sub>C</sub> ) Volume	Volume
	d (Pb) Fre	e Solder (T <sub>C</sub> )	Volume mm <sup>3</sup>
Table 2 - Lea	d (Pb) Fre Volume	e Solder (T <sub>C</sub> ) Volume	
Table 2 - Lea Package	d (Pb) Fre Volume mm <sup>3</sup>	e Solder (T <sub>C</sub> ) Volume mm <sup>3</sup>	mm <sup>3</sup>
Table 2 - Lea Package Thickness	Volume           mm³           <350	e Solder (T <sub>C</sub> ) Volume mm <sup>3</sup> 350 - 2000	mm <sup>3</sup> >2000

## **Reference JDEC J-STD-020**

Powerina Business Worldwide

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak	<ul> <li>Temperature min. (T<sub>smin</sub>)</li> </ul>	100°C	150°C	
	<ul> <li>Temperature max. (T<sub>smax</sub>)</li> </ul>	150°C	200°C	
	<ul> <li>Time (T<sub>smin</sub> to T<sub>smax</sub>) (t<sub>s</sub>)</li> </ul>	60-120 Seconds	60-120 Seconds	
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>		3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL)		183°C	217°C	
Time at liquidous (t	)	60-150 Seconds	60-150 Seconds	
Peak package body	temperature (T <sub>P</sub> )*	Table 1	Table 2	
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature $(T_c)$		20 Seconds**	30 Seconds**	
Average ramp-down rate (Tp to Tsmax)		6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.	

 $^{\ast}$  Tolerance for peak profile temperature (T\_p) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature  $(t_p)$  is defined as a supplier minimum and a user maximum.

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